



## Final Product/Process Change Notification

Document #:FPCN22724X

Issue Date:11 Oct 2019

<b>Title of Change:</b>	PQ DFN8 drivers capacity expansion in OSPI Tarlac turnkey enablement	
<b>Proposed First Ship date:</b>	15 Feb 2020 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or Elmer.Milar@onsemi.com	
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or Andy.Esteva@onsemi.com	
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
<b>Marking of Parts/ Traceability of Change:</b>	Products assembled in OSPI Tarlac will have a Month Code marking of "M "	
<b>Change Category:</b>	Assembly Change, Test Change	
<b>Change Sub-Category(s):</b>	Manufacturing Site Change/Addition	
<b>Sites Affected:</b>		
<b>ON Semiconductor Sites</b>	<b>External Foundry/Subcon Sites</b>	
ON Semiconductor Tarlac, Philippines	None	
<b>Description and Purpose:</b>		
<b>Facility</b>	<b>Before Change Description</b>	<b>After Change Description</b>
Assembly Site	UTAC (TH3) Thailand Seremban SBN  Mold Compound = MC G700LTD	UTAC (TH3) Thailand Seremban (SBN) OSPI Tarlac (PHM)  All Assembly BOMs are going to be the same except for the Mold Compound. Mold Compound (Tarlac) = MC G770 HMD
Test Site	UTAC (TH6) Thailand Seremban SBN	UTAC (TH6) Thailand Seremban (SBN) OSPI Tarlac (PHM)

**Reliability Data Summary:**

QV DEVICE NAME: NCP81258MNTBG

RMS : 57784

PACKAGE : DFN8 2\*2\*0.9

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc 13.2V	1008 hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias 13.2V	192 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C 3 IR @ 260 deg C	-	
RSH	J-STD-002	Ta=265C, 10 sec	-	0/45
SD	J-STD-002or JESD22 B102	Ta=245C		0/45
PD	JESD22 B100,B108	Applicable POD/Case Outline		0/30

**Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [\*\*PCN Customized Portal\*\*](#).

Part Number	Qualification Vehicle
NCP81166MNTBG	NCP81258
NCP81166HMNTBG	NCP81258
NCP81161MNTBG	NCP81258
NCP81151MNTBG	NCP81258
NCP81151FHMNTBG	NCP81258
NCP81151FDMNTBG	NCP81258
NCP81151BMNTBG	NCP81258
NCP5901MNTBG	NCP81258
NCP5901BMNTBG	NCP81258
NCP81258MNTBG	NCP81258
NCP81258HMNTBG	NCP81258
NCP81258FHMNTBG	NCP81258
NCP81258FDMNTBG	NCP81258